

## Features

- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Low profile, typical thickness 1.0mm
- Solder dip 260 °C, 10 s
- AEC-Q101 qualified



Package: eSGB(SMAF)

## Applications

For uses in low voltage, high frequency inverters, free wheeling and polarity protection applications.

## Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	LSL56	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V
Maximum RMS Voltage	$V_{RMS}$	42	V
Maximum DC Blocking Voltage	$V_{DC}$	60	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	$I_{FSM}$	80	A
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Storage Temperature Range	$T_{STG}$	-55 to +150	°C

## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Instantaneous Forward Voltage	$I_F=1\text{A}, T_A=25^\circ\text{C}$	$V_F$	-	0.33	0.38	V
	$I_F=2\text{A}, T_A=25^\circ\text{C}$		-	0.36	0.41	
	$I_F=5\text{A}, T_A=25^\circ\text{C}$		-	0.43	0.50	
	$I_F=5\text{A}, T_A=125^\circ\text{C}$		-	0.38	-	
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$	$I_R$	0.5			mA
	$T_A=125^\circ\text{C}$		100			
Typical Junction Capacitance	4.0 V, 1 MHz	$C_J$	330			pF
Typical Thermal Resistance <sup>1)</sup>	Junction to Lead	$R_{\theta JL}$	30			°C/W

Note1: Thermal resistance from junction to lead, mounted on PCB with 8.0×8.0mm copper pads

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

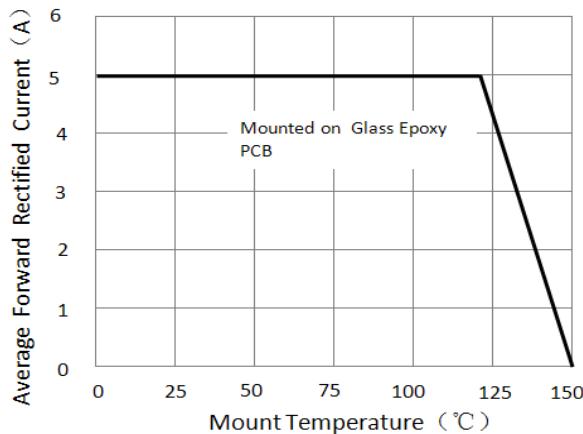


Figure 1. Forward Current Derating Curve

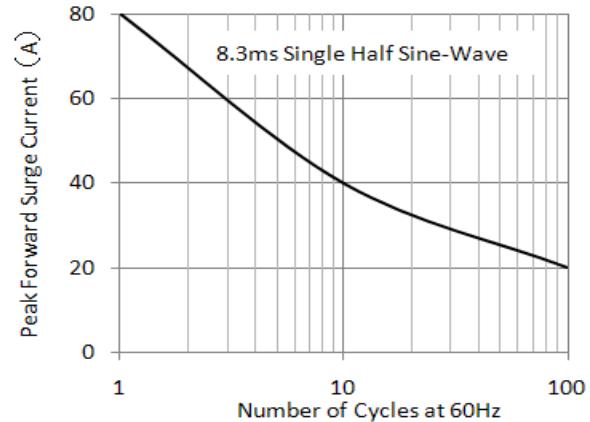


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

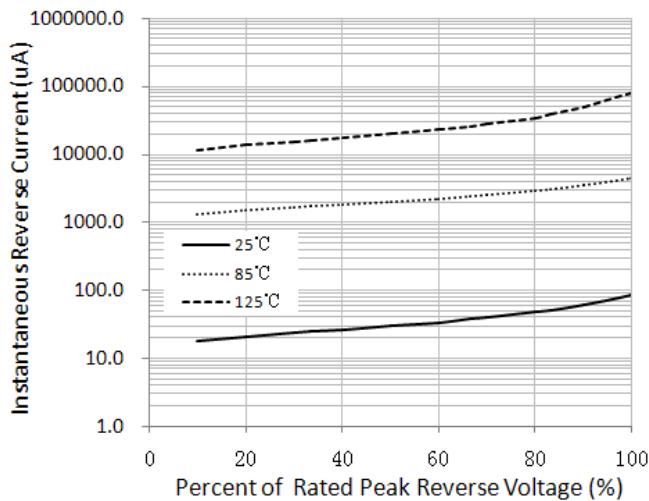


Figure 3. Typical Reverse Characteristics

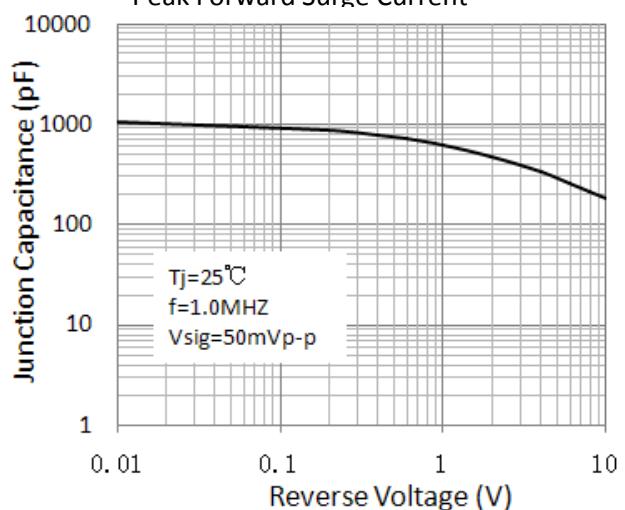


Figure 4. Typical Junction Capacitance

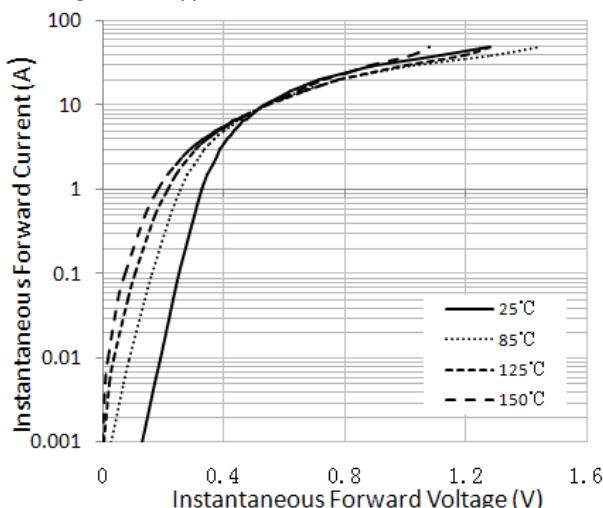
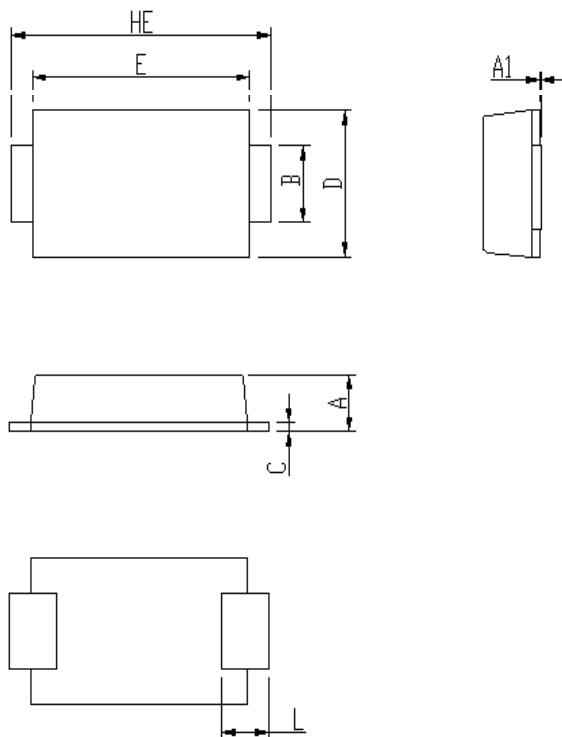


Figure 5. Typical Instantaneous Forward Characteristics

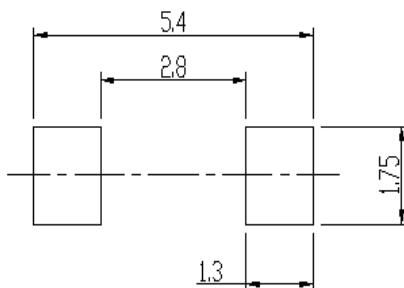
## Package Outline Dimensions

eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



## Packing Information

Reel Size	Quantity/Reel	Quantity/Inner Box	Quantity/Carton
7"	3K	21K	84K
13"	10K	20K	180K

## Tape & Reel Specification

